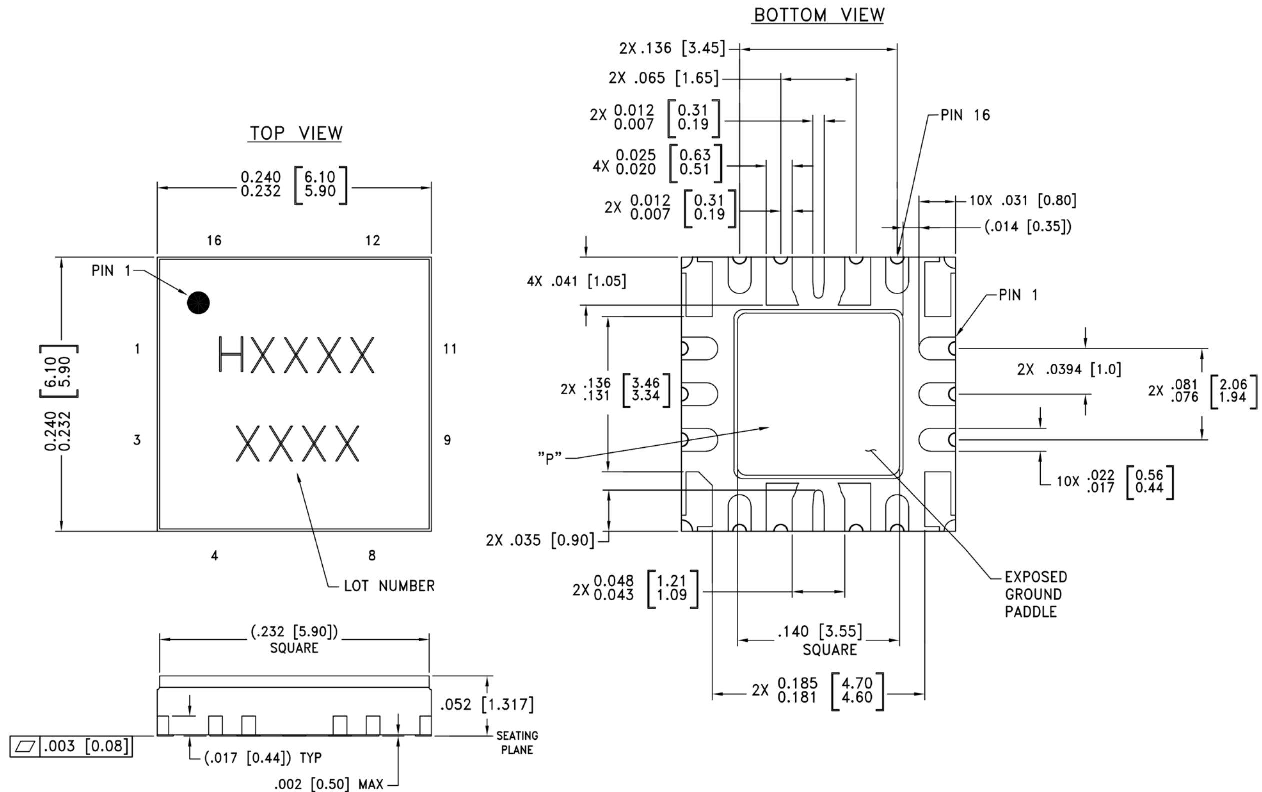
Hittite MICROWAVE CORPORATION

PACKAGE OUTLINES

LS6 – LEADLESS CERAMIC POWER AMPLIFIER SMT PACKAGE

Suggested LS6 PCB Land Pattern



NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating [2]	Package Marking [1]
HMC7229LS6	ALUMINA WHITE	Gold over Nickel	N/A [3]	H7229 XXXX

[1] 4-Digit lot number XXXX.
[2] Max peak reflow temperature of 260 °C.
[3] Not Applicable to air cavity packages.

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